

A background image showing a Ferrari pit crew in red uniforms working on a red race car. A digital timer at the top displays '1.8 SEC' in red. The car has 'AI' and 'G2C' branding.

The Top Assisting Partner in the AI Supply Chain

*Empowering the success of clients across different ecosystems
through high-level collaboration*

C SUN 志聖工業

2026 Q1 Investor's meeting

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward-looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design in, time to market, market competition, industrial cyclicity, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations. global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward-looking statements. Except as required by law. C Sun undertakes no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

G2C+ Alliance: The Platform Advantage

Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)

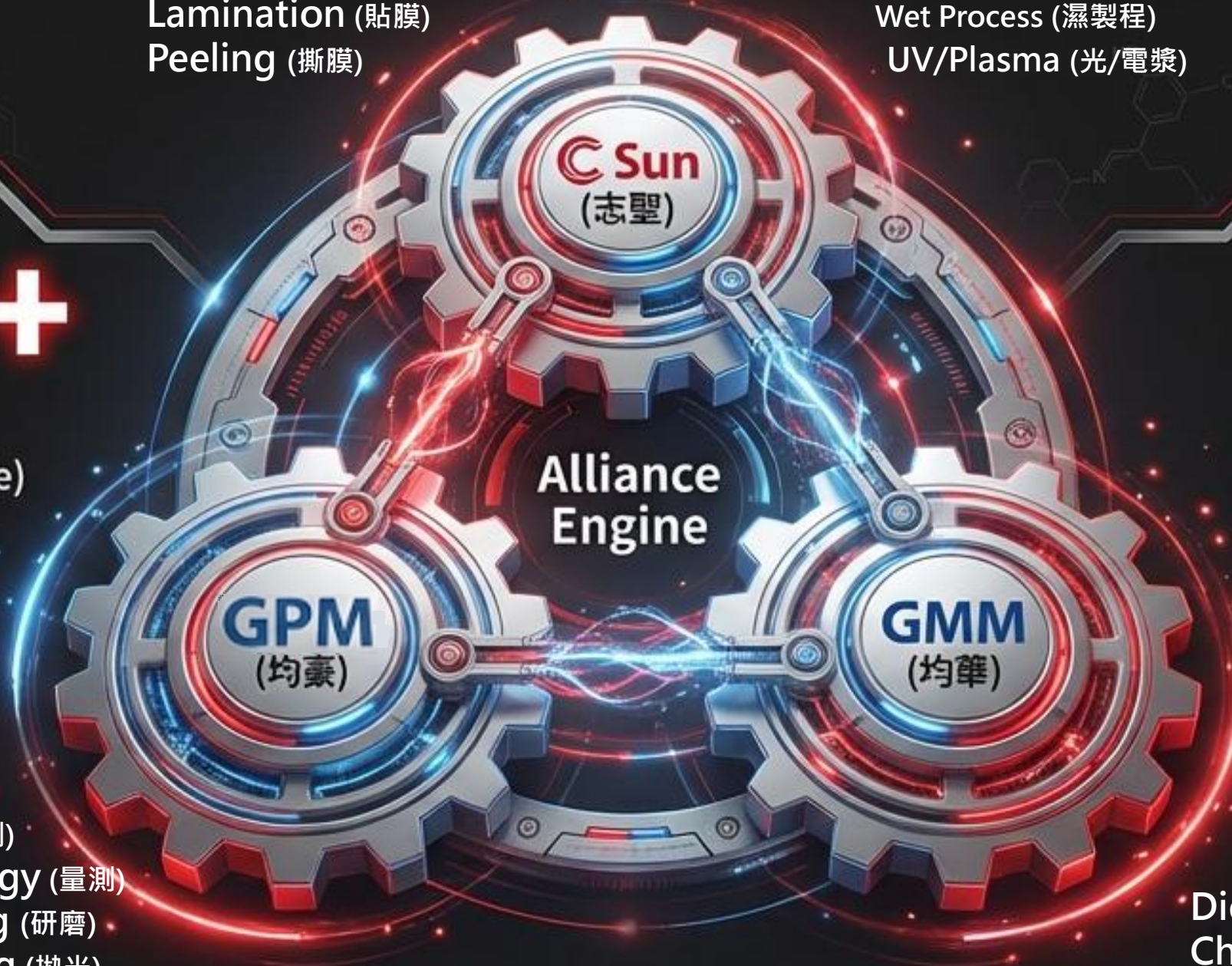
Thermal (熱)
Wet Process (濕製程)
UV/Plasma (光/電漿)

1,800+

聯盟總人數
(Total Alliance Workforce)



AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)



>600

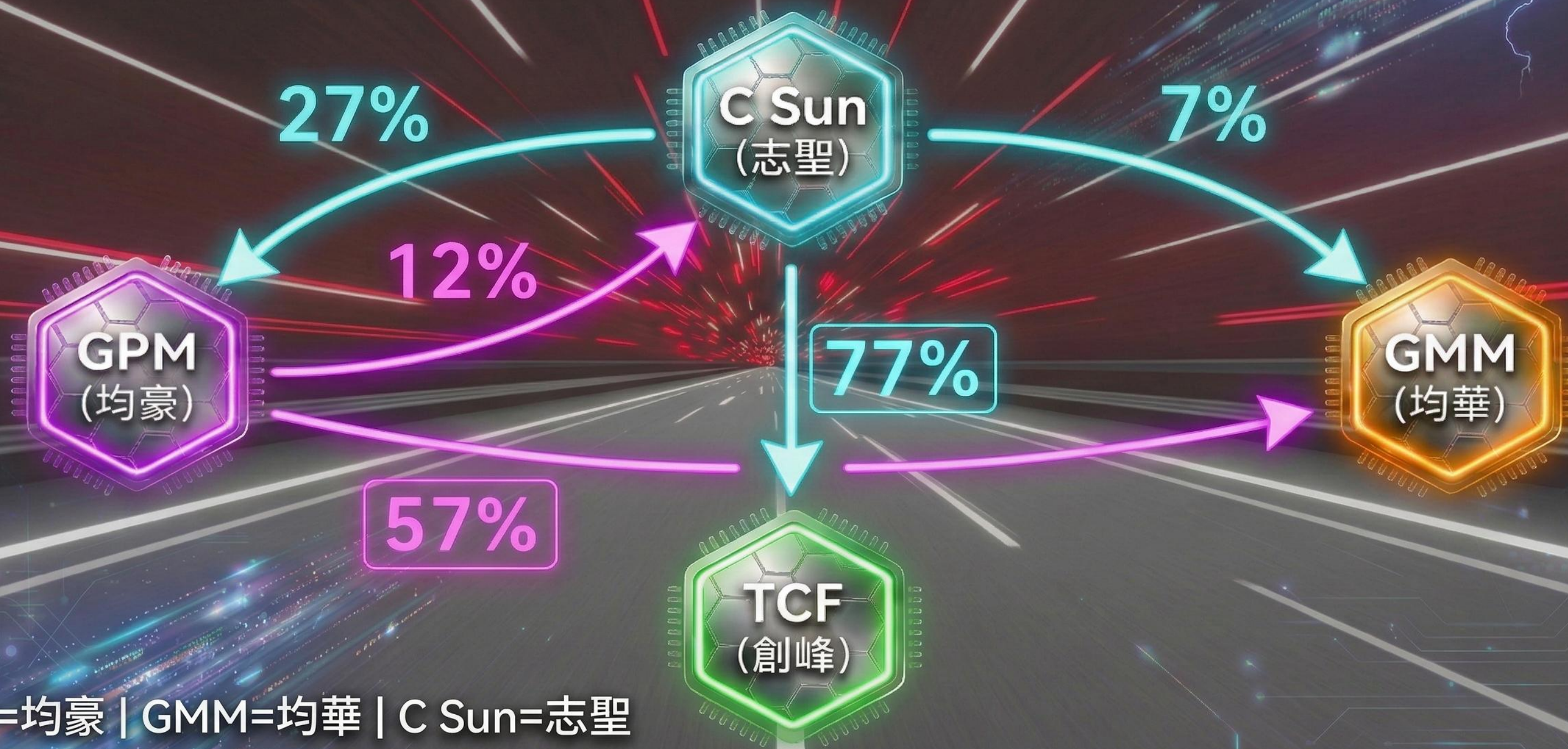
研發人員
(R&D Personnel)



Die Attach (黏晶)
Chip Sorter (揀晶)

G2C+ ALLIANCE

Cross Holding Structure



Professional Collaborative Team on the **AI** Track

Continuous Recognition from
Champion Team



2023:
Excellent Production Support
(卓越量產支援)



2024:
Outstanding Improvement
(傑出持續改善)



2025:
Excellent Production Support
(卓越量產支援)

Financial Review

Selected Items from Statements of Comprehensive Income
(In NT\$ millions unless otherwise noted)

**2026
Jan**

2025

4Q25

3Q25

1H25

2024

**4Q25
QoQ**

**2025
YoY**

Revenue-Consolidated

994

6,102

1,747

1,536

2,819

4,818

13.7%

26.6%

Gross Margin%

43.3%

44.1%

44.2%

42.3%

41.2%

-0.1ppts

+2.1ppts

Operating Expense

(1,760)

(493)

(526)

(741)

(1,347)

-6.3%

30.7%

Operating Expense%

28.9%

28.2%

34.3%

30.5%

28.0%

-2.3ppts

+0.9ppts

RD Expense

(543)

(170)

(164)

(208)

(362)

3.9%

49.8%

RD Expense %

8.9%

9.8%

10.7%

7.4%

7.5%

-0.9ppts

+1.4ppts

Operating Margin%

14.5%

15.9%

10.0%

16.1%

13.2%

+5.9ppts

+1.3ppts

Non-Operating Items

243

56

134

54

344

-58.4%

-29.1%

Net Income Attributable to Shareholders of the Parent Company

830

260

212

358

719

23.1%

15.4%

Net Profit Margin%

13.6%

14.9%

13.8%

12.7%

14.9%

+1.1ppts

-1.3ppts

EPS (NT\$D)

5.5

1.72

1.4

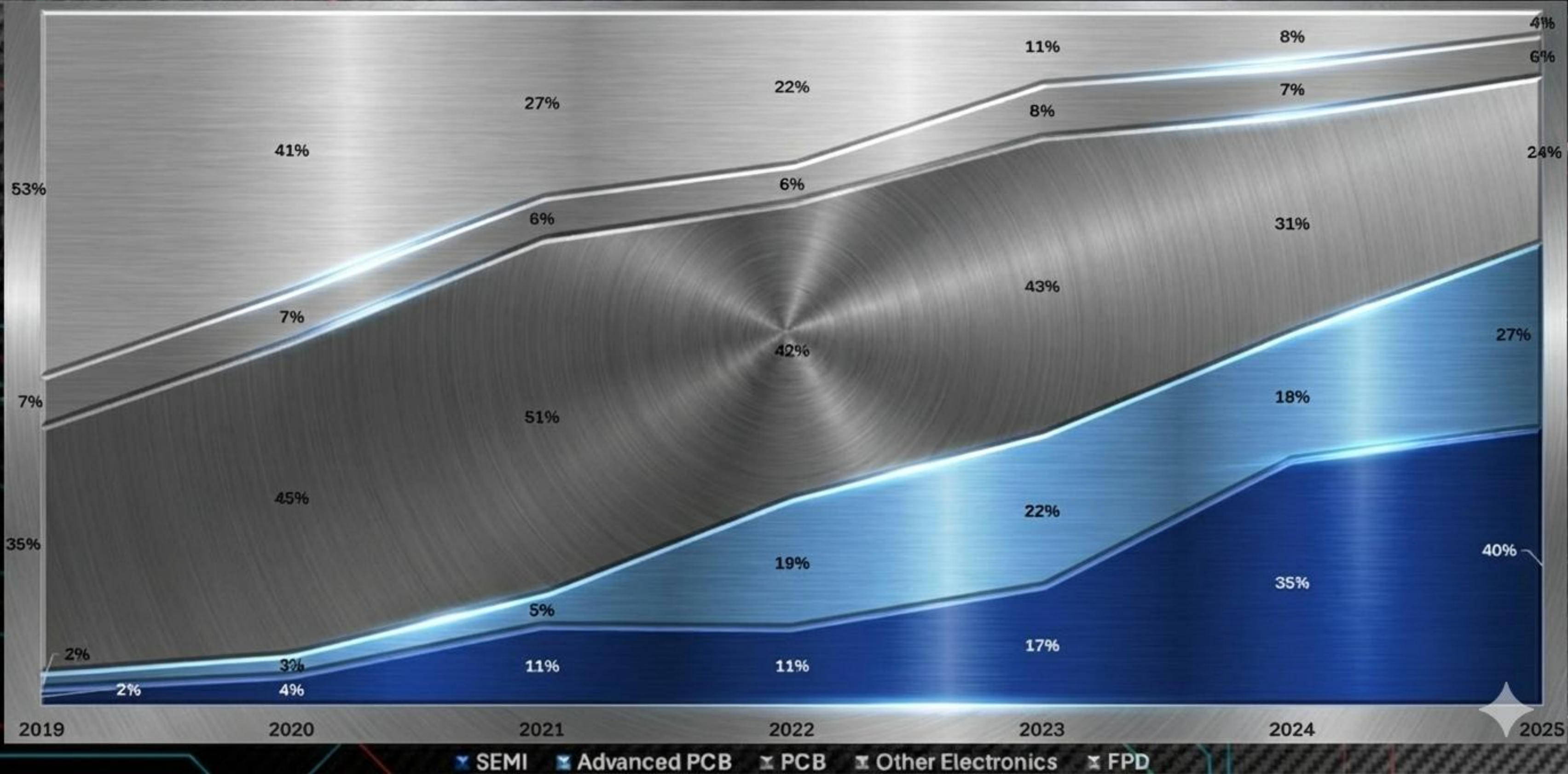
2.38

4.8

22.9%

14.6%

Revenue Composition



2025 Financial Highlights: Structural Transformation & Record Highs

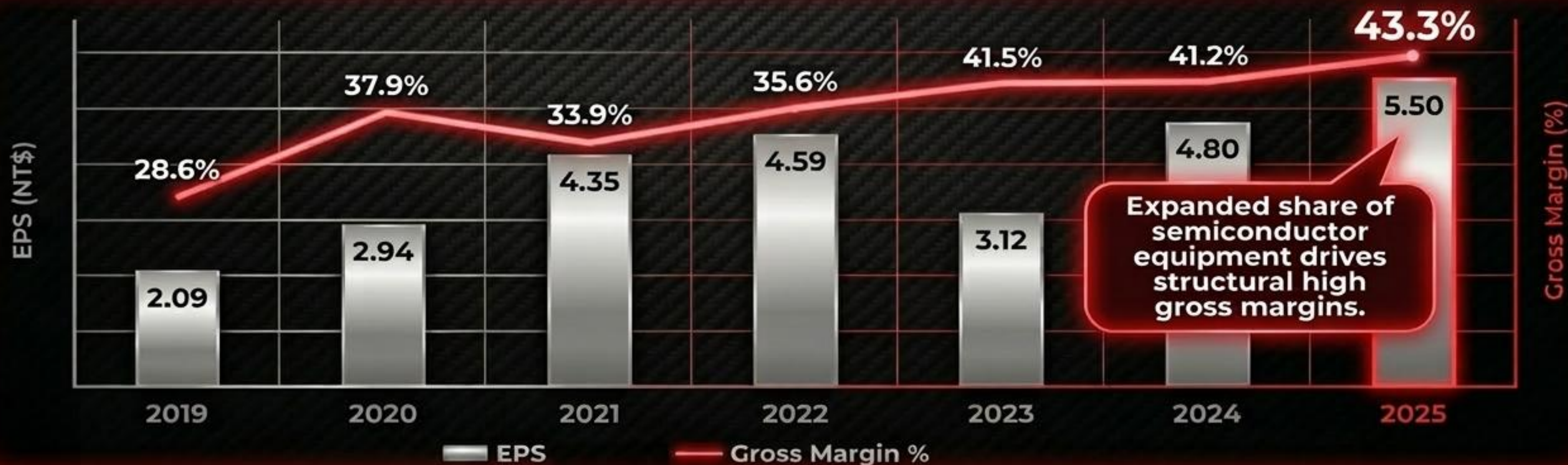
2025 Revenue

NT\$ 6.1 Billion

Record High

2025 EPS

NT\$ 5.50



2026 Opening: Record-High Single-Month Revenue

MoM
+64.60%



MoM



994
NT\$ Million



YoY

YoY
+124.10%

Customers' CAPEX continues to flow in, providing sustainable momentum for future growth.

Dynamically aligning with customers' delivery schedules.





TSMC, intel, GF
FOUNDRY ACCESS TRACK

SoIC

InFO

EMIB

X-CUBE

WMCM

TSMC | Intel | GF

OSAT

AI substrate & HDI

AI SUBSTRATE & HDI
ACCESS TRACK

ABF

SAP

HDI

mSAP

OSAT
ACCESS TRACK

Adv. PLP

SoIC

InFO

FlipChip

FoCoS

FoPLP

CoWoS

CoWoS

CoWoP

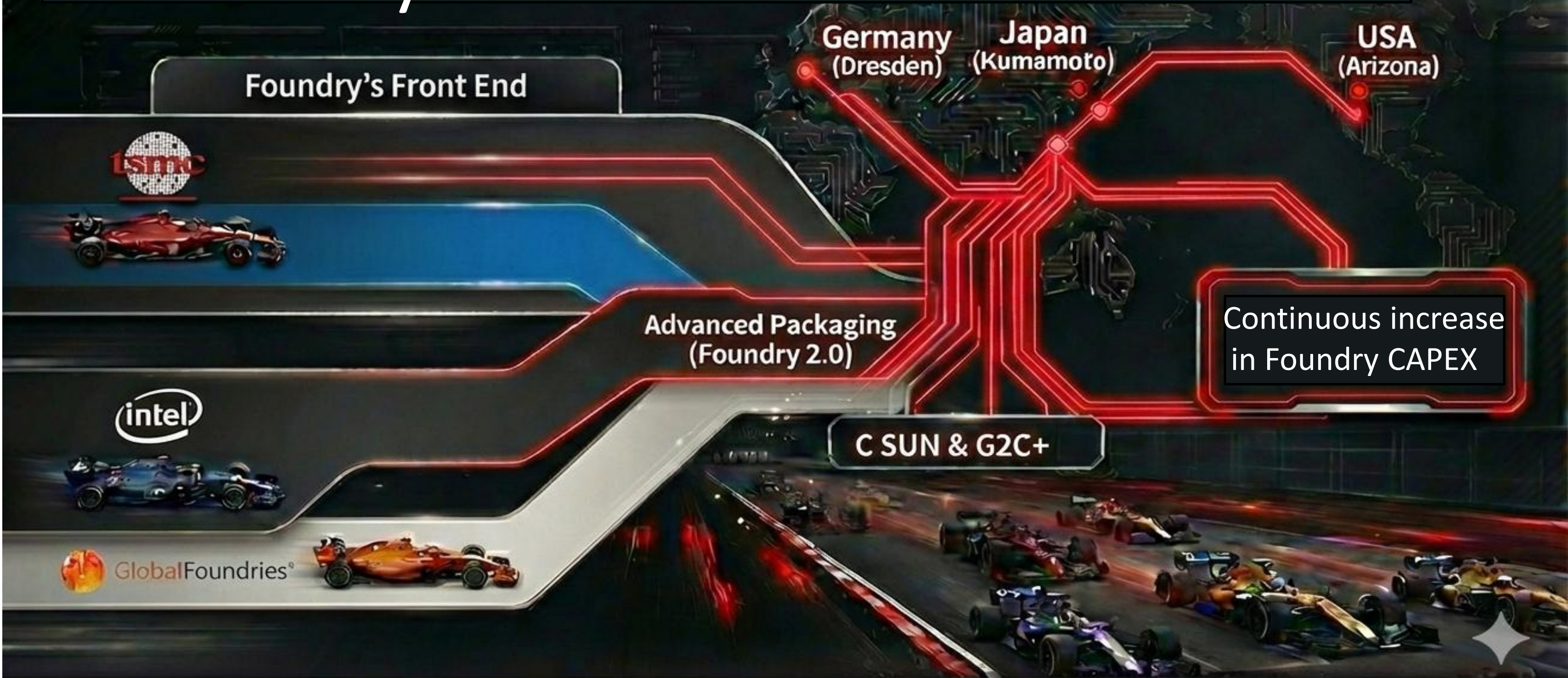
CoWoP

GRAND CIRCUIT

Advanced Packaging
GRAND CIRCUIT

Growth Engine I: Following the Leader

- Foundry 2.0 Glocalization



Growth Engine II: AI Chip Diversification drives Process Fragmentation

*AI diversification
drives **Process
Fragmentation***

OSAT Expansion
(ASE, Amkor, SPIL)

Technology Shift → FOPLP
(Panel Level)

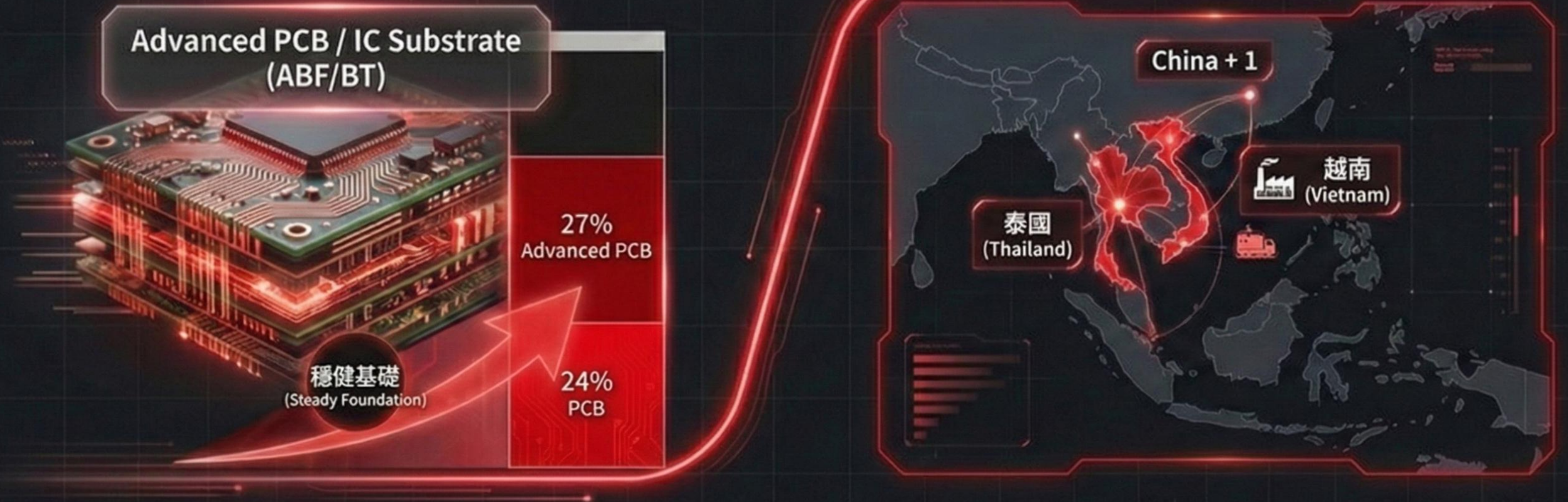
HBM Memory Demand
(Micron, SK Hynix)

DATA

HBM expansion boosts the demand for Thermal (Oven) equipment.

Growth Engine III: High-End PCB

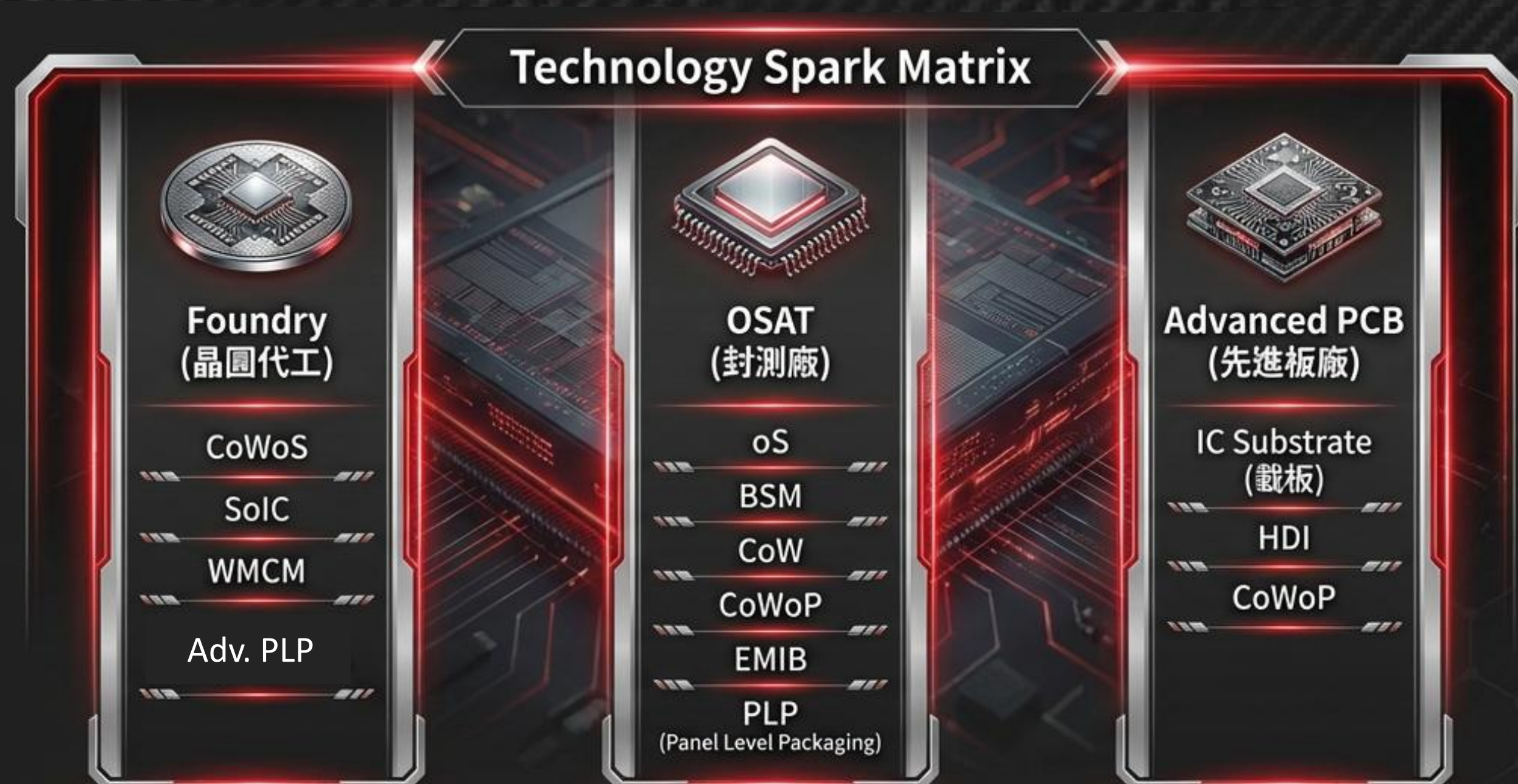
Product Mix Upgrade & Regional Shift



Optimizing product mix **drives ASP enhancement**, continuously improving profitability structure.



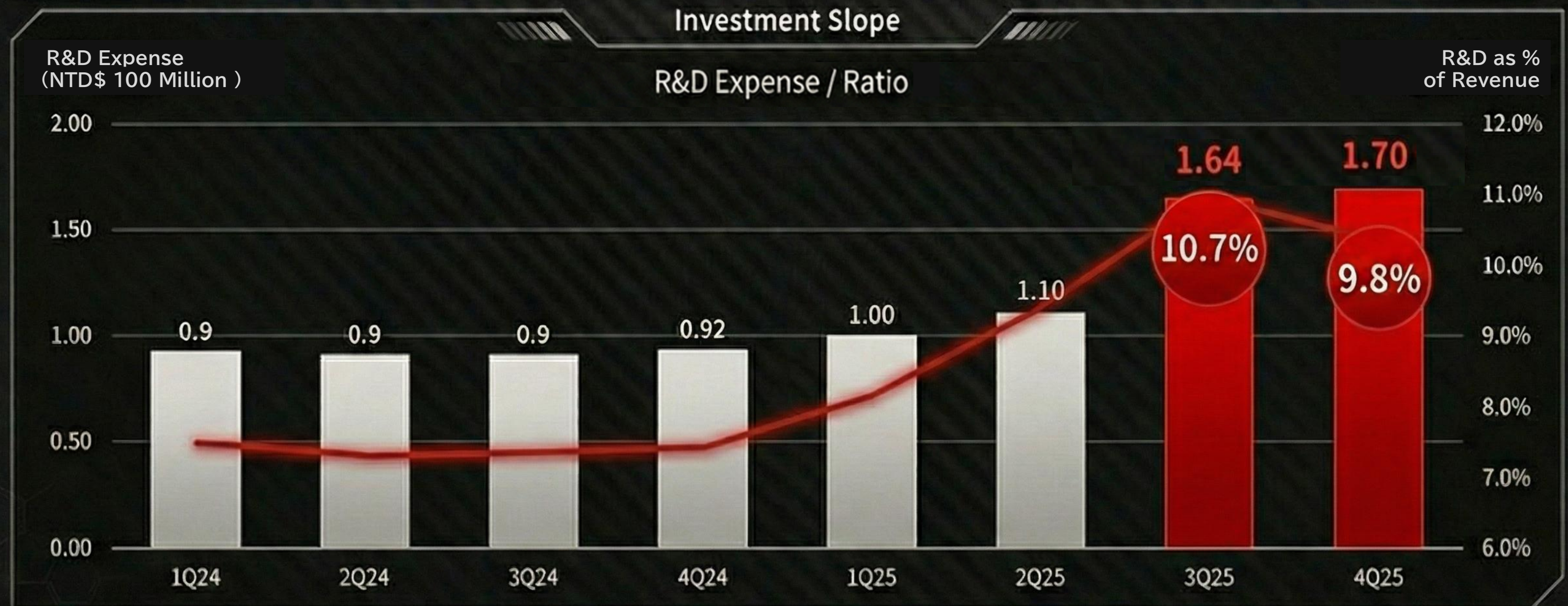
Technology Roadmap: Full Spectrum Coverage



Not only capitalizing on current advanced packaging dividends, but already positioned for future new process demands over the next 3 years.

R&D Resource Allocation & Tech Upgrade

Next-Gen Processes & Equipment Upgrade for Advanced Packaging Supply Chain



Investments during the tech upgrade phase will support growth momentum for the next 3-5 years.

Nesting to Attract Phoenixes: R&D Center and Global Expansion

NT\$ 1.82 Billion

Building an R&D center to lay the foundation for the development of diverse, forward-looking equipment.



USA

台中水湳研發中心
(Taichung Shuinan R&D Center)

The Innovation Hub

精科二廠
(Jingke Plant 2)

Capacity Expansion

Japan

NT\$ 1.48 Billion

Acquiring factories and facilities to ensure future production capacity is secured.

F1 ADVANCED PACKAGING GRAND PRIX

Foundry Main Track
CoWoS / SoIC / WMCM



OSAT Track

PLP / oS / Bumping / CoW / EMIB



AI Substrate & HDI Track
IC Substrate / HDI

